Tien Hsi Lee

List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/3589604/publications.pdf

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		1937685	1588992
15	70	4	8
papers	citations	h-index	g-index
15	15	15	73
all docs	docs citations	times ranked	citing authors

#	Article	lF	Citations
1	Near-Field Electrospun Piezoelectric Fibers as Sound-Sensing Elements. Polymers, 2018, 10, 692.	4.5	28
2	Annihilating Pores in the Desired Layer of a Porous Silicon Bilayer with Different Porosities for Layer Transfer. Scientific Reports, 2019, 9, 12631.	3.3	12
3	Inhibition Effect of a Laser on Thickness Increase of p-Type Porous Silicon in Electrochemical Anodizing. Journal of the Electrochemical Society, 2016, 163, H265-H268.	2.9	11
4	Self-Powered, Hybrid, Multifunctional Sensor for a Human Biomechanical Monitoring Device. Applied Sciences (Switzerland), 2021, 11, 519.	2.5	5
5	Sharpening Si Nanocrystals on the Bulk Surface by Nanoscale Electrochemistry through Controlling the Hole Current with the Irradiation of Near-Infrared Laser. Journal of the Electrochemical Society, 2016, 163, E258-E262.	2.9	3
6	Forming a Photoluminescent Layer on Another Surface in the Dark through Lasering of N-Type Silicon in an Electrolyte. ACS Omega, 2020, 5, 26497-26503.	3.5	3
7	Nanoscale Layer Transfer by Hydrogen Ion-Cut Processing: A Brief Review Through Recent U.S. Patents. Recent Patents on Nanotechnology, 2017, 11, 42-49.	1.3	3
8	Communicationâ€"Effect of Free-Carrier Absorption on an Anodized Silicon Surface for Producing Dense and Uniform Nanocrystals. Journal of the Electrochemical Society, 2018, 165, H99-H101.	2.9	2
9	Rapid Fabrication of 100 nm or Thinner Fully Depleted Silicon-on-Insulator Materials for Ultralow Energy Consumption. ACS Applied Nano Materials, 2018, 1, 2414-2420.	5.0	2
10	Low-temperature rough-surface wafer bonding with aluminum nitride ceramics implemented by capillary and oxidation actions. Ceramics International, 2022, 48, 8766-8772.	4.8	1
11	Thermal Stress Induced Thin Film Transfer from Single-crystal Silicon Layer on Sapphire Substrate. Integrated Ferroelectrics, 2013, 144, 73-78.	0.7	0
12	Communication—Eliminating Thickness Measurement Uncertainty of Capacitive Displacement Sensor in High Resistivity Substrate by Photoconduction. ECS Journal of Solid State Science and Technology, 2017, 6, P323-P325.	1.8	0
13	Utilization of Low Wavelength Laser Linking with Electrochemical Etching to Produce Nano-Scale Porous Layer on p-Type Silicon Wafer with High Luminous Flux. ECS Journal of Solid State Science and Technology, 2021, 10, 016003.	1.8	0
14	Low-Temperature Rough-Surface Wafer Bonding with AlN/AlN Via Oxygen Plasma Activation. ECS Transactions, 2022, 108, 49-50.	0.5	0
15	Low-Temperature Rough-Surface Wafer Bonding with AlN/AlN Via Oxygen Plasma Activation. ECS Meeting Abstracts, 2022, MA2022-01, 1046-1046.	0.0	0